



# Chip Seals

**Y. Richard Kim**

Department of Civil, Construction, and Environmental Engineering  
North Carolina State University

**Lunch and Learn**  
**Value Management Program, NCDOT**  
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# Outline

- ❑ Chip Seal Basics
- ❑ Test Specimen Fabrication Methods
- ❑ Performance Test Methods
- ❑ Desirable Aggregate Characteristics
- ❑ Desirable Emulsion Properties
- ❑ Performance-Engineered Mix Design
- ❑ Optimal Rolling Protocols
- ❑ Construction Variability and PRS
- ❑ Key Implementation Points



# Chip Seals

## *Definition*

- ❑ A single layer of asphalt binder (hot applied or emulsion) that is covered by embedded aggregate (one stone thick)
- ❑ Also commonly referred to as “seal coat”



# Benefits

- ❑ Seals the underlying pavement against water intrusion
- ❑ Enhance or restore skid resistance
- ❑ Enrich the pavement surface to prevent the distresses caused by oxidation.
- ❑ Can effectively seal fine cracks unless the cracks are indications of structural distresses
- ❑ Low cost
- ❑ Fast construction



# Chip Seal Power in NC

	2017		2022	
	Chip Seal	HMA	Chip Seal	HMA
Miles Paved	4,479 (50.0%)	4,483 (50.0%)	1,665 (39.0%)	2,622 (61.0%)
Dollars Spent	\$61.9 million (16.3%)	\$317 million (83.7%)	\$25.9 million (10.1%)	\$230 million (89.9%)
Dollar per Mile	\$13,825	\$70,738	\$15,563	\$87,764



# Critical Distresses

## ❑ Raveling

- Loss of aggregate
- Windshield damage
- Safety concern



## ❑ Bleeding

- Over application of emulsion
- Aggregate loss or embedment
- Safety concern



# Chip Seal Types

- ❑ Single Seal: Single layer of uniformly graded aggregate on a single layer of binder
- ❑ Double Seal: Two consecutive applications of both binder and aggregate
  - The aggregate in the second application is typically about half the nominal size of the first.
- ❑ Triple Seal: Three consecutive applications of both binder and aggregate
  - Choke stone is used as the aggregate in the final application.
  - Prevents aggregate particles from dislodging.



# Solutions for Well-Performing Chip Seals

- ❑ Quality of materials, design application rates, and construction quality control are all important for well-performing chip seals!
- ❑ Need a comprehensive **system** to improve the quality of chip seals
  - Performance specifications for materials
  - Performance-engineered mix design
  - Performance-related specifications for construction quality assurance

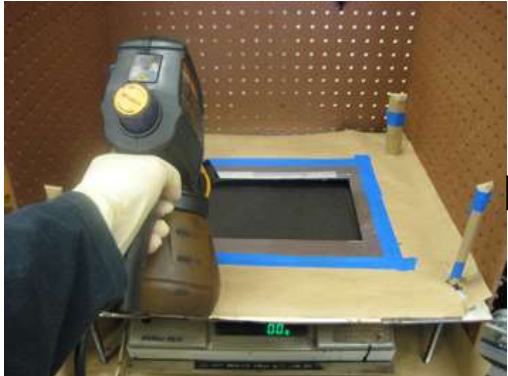




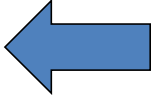
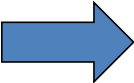
# Chip Seal Specimen Fabrication Methods



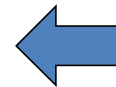
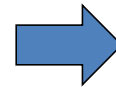
# Laboratory Fabrication Using ChipSS



# Field Sampling Procedure



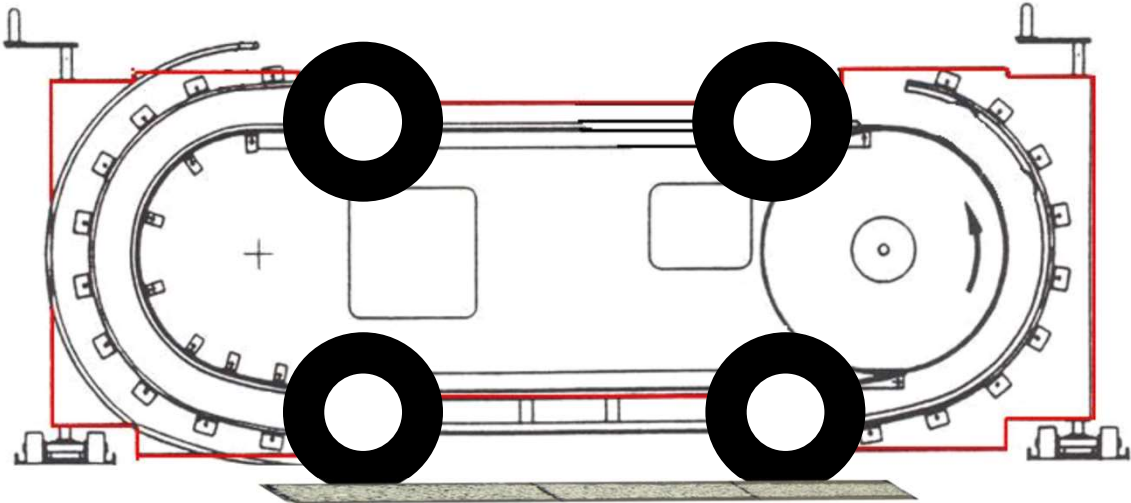
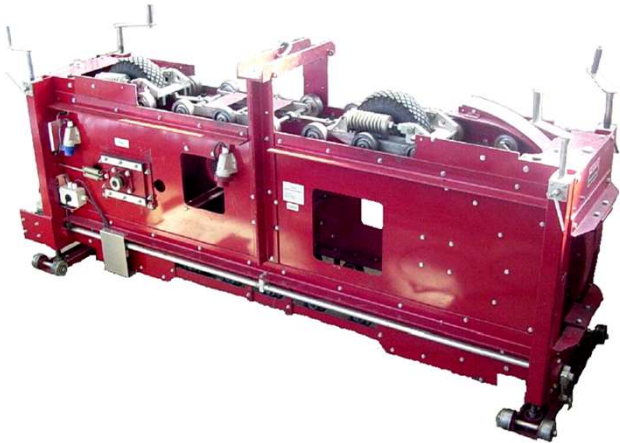
# Gathering Samples and Delivery



# Chip Seal Performance Test Methods



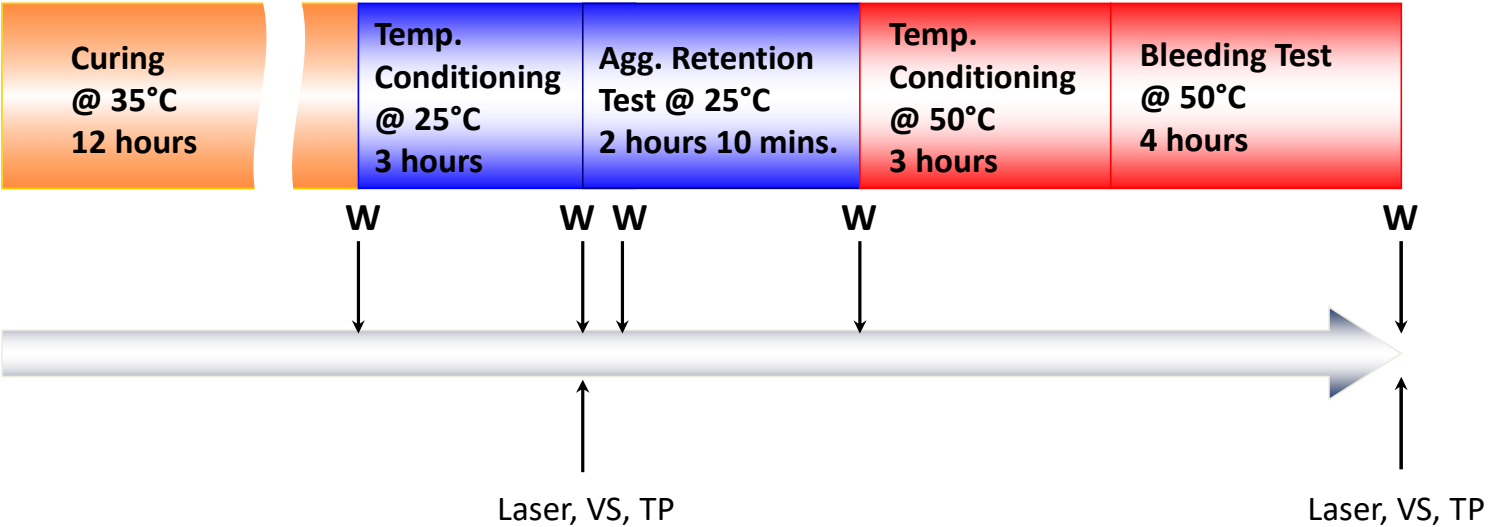
# Third-Scale Model Mobile Loading Simulator (MMLS3)



# MMLS3 Chip Seal Test Preparation



# MMLS3 Test Procedure



**W: Measurement of the Specimen Weight**  
**Laser: Laser Profiler Test**  
**VS: Visual Survey**  
**TP: Transverse Profiling**



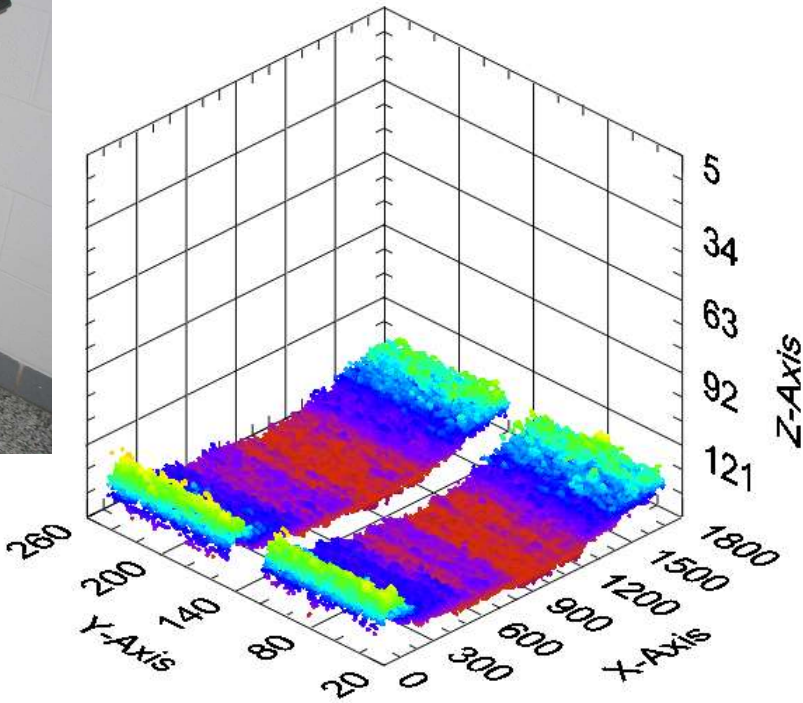


# Sand Patch Test (ASTM E965)

- ❑ Spread a predetermined volume of sand into circle on pavement surface
  - Use area of circle and known volume of sand to determine mean texture depth



# Laser Profiler

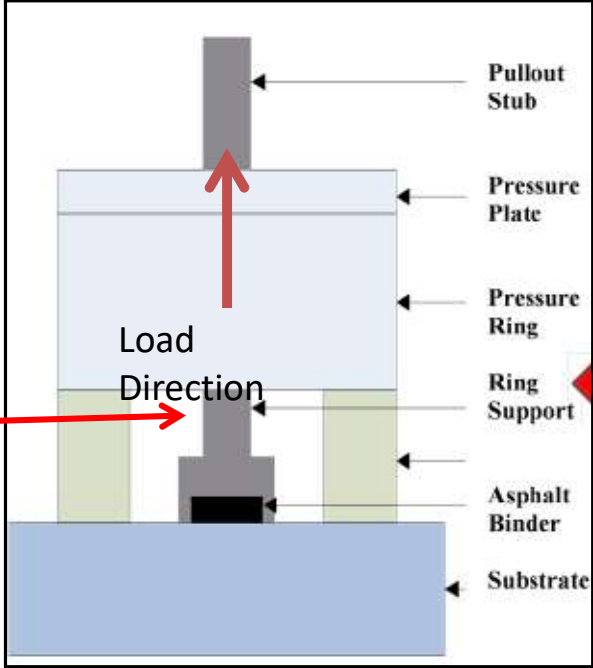
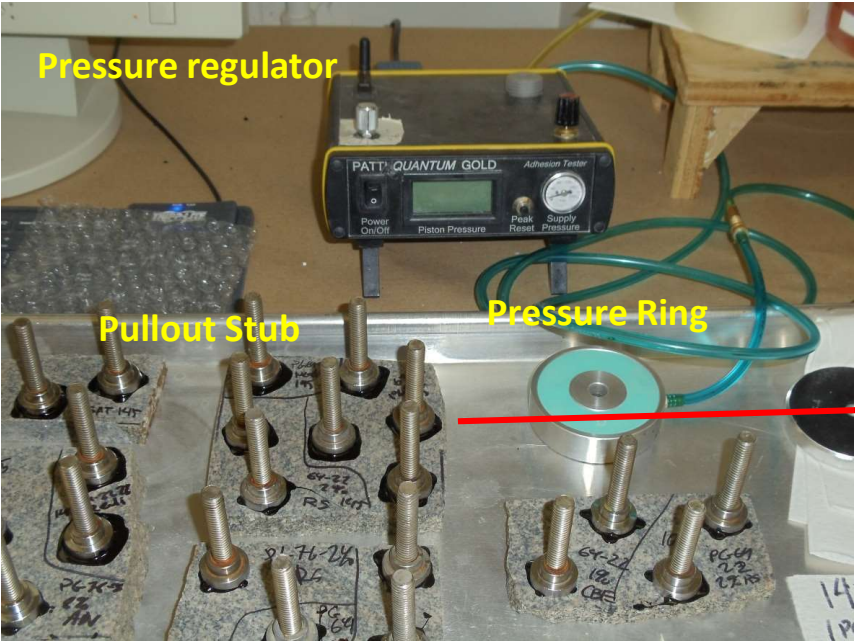


## Vialit Test

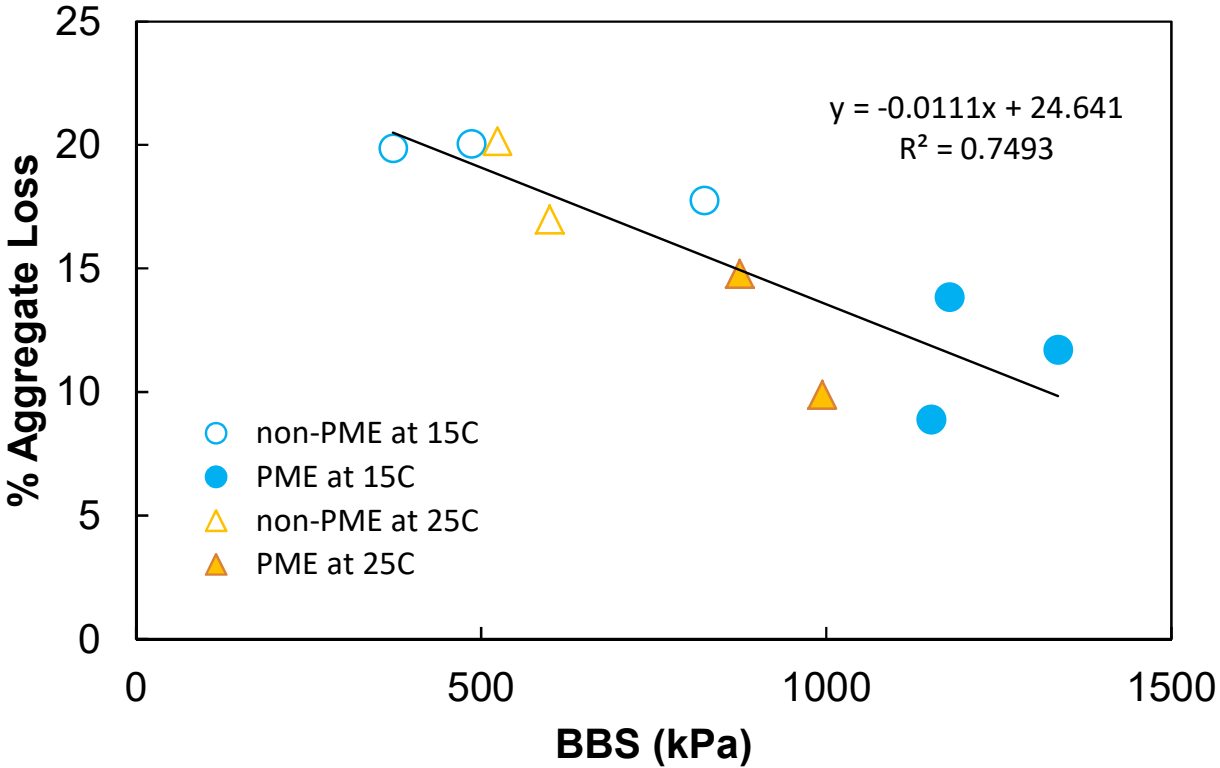
- ❑ Curing samples in the oven at 35°C for 24 hours.
- ❑ Flip over samples to remove excess aggregate.
- ❑ Place samples upside down on a device.
- ❑ Drop the ball three times within 10 sec.
- ❑ Measure the weight of samples.



# Binder Bond Strength (BBS) Test



# Vialit Aggregate Loss vs. BBS



# Desirable Aggregate Characteristics



# Important Aggregate Properties

- Gradation
- Fine Content
- Particle Shape: Flakiness Index
- Abrasion Resistance
- Strength
- Bulk Specific Gravity
- Loose Unit Weight
- Absorption



# Material Selection

## *Aggregate*

### □ Size

- Establishes the thickness of the chip seal
- Most agencies use a nominal size that ranges from 3/8 in (9.5 mm) to 1/2 in (12.7 mm)
- Larger aggregate particle sizes are more durable and less sensitive to variations in binder application rate
- Larger particles lead to greater noise and windshield damage if dislodged

### □ Gradation

- Best to have uniform gradation
- Limiting dust is critical





# Material Selection

## *Aggregate*

- ❑ Aggregate shape
  - Angular particles best
  - Rough particles improve bonding
  - Cubical particles desirable because traffic does not have a significant effect on the final orientation of aggregate
- ❑ Synthetic aggregate (Lightweight)
  - Produced by heating shale, clay or slate
    - Expands to create a porous, lightweight aggregate.
  - Advantages
    - Low mass, will not break windshields
    - Good skid resistance
    - Tend to have more uniform gradation



# Material Selection

## *Aggregate*

- ❑ Pre-coated aggregate
  - Only used with hot-applied binder
  - Improves aggregate retention
  - Expedites construction
  - Minimizes dust and moisture issues
  - 0.8 to 2.4 gal/yd<sup>3</sup> binder application rate



# Effect of Gradation

*MMLS3 Test Results*

Before Loading

After Agg. Retention Test

After Bleeding Test



**Granite 78M with Less Uniform Gradation**

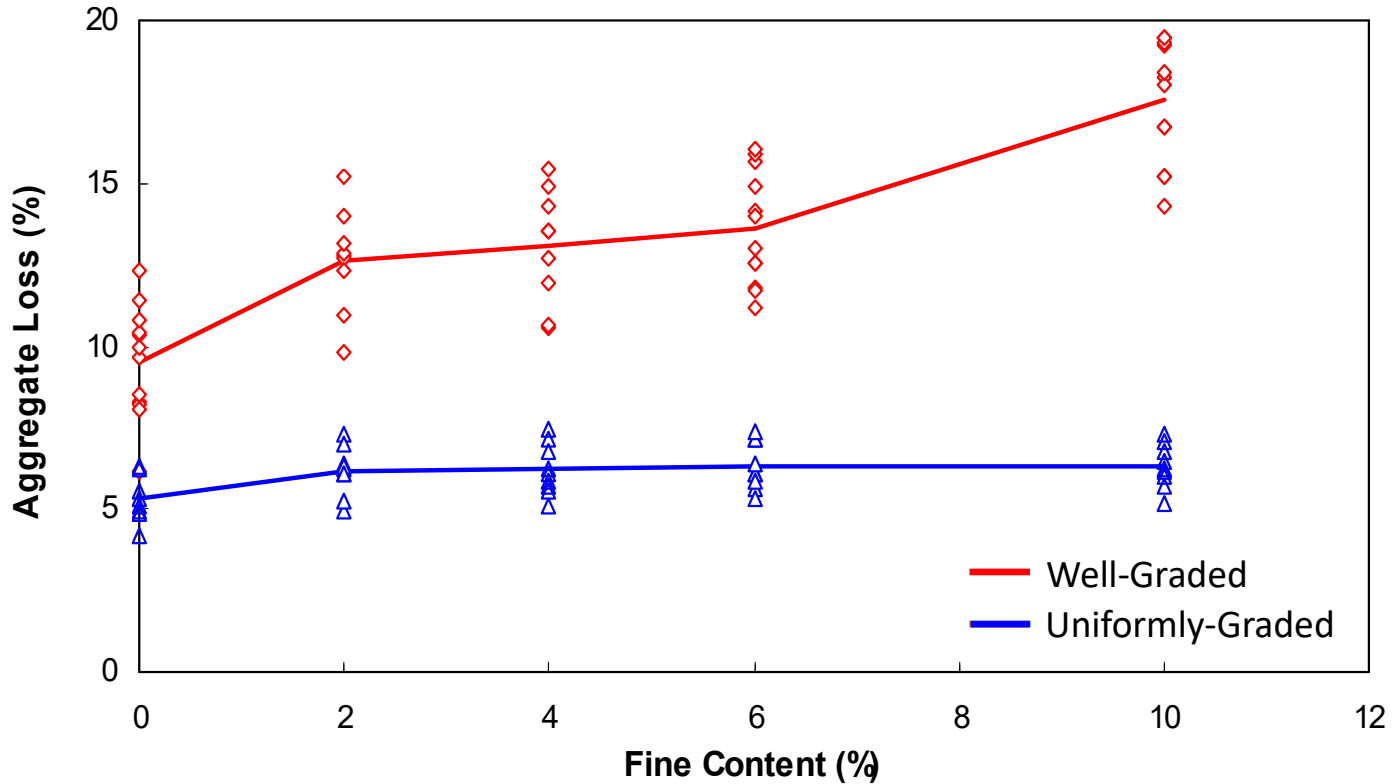


**Light-weight 5/16" with More Uniform Gradation**

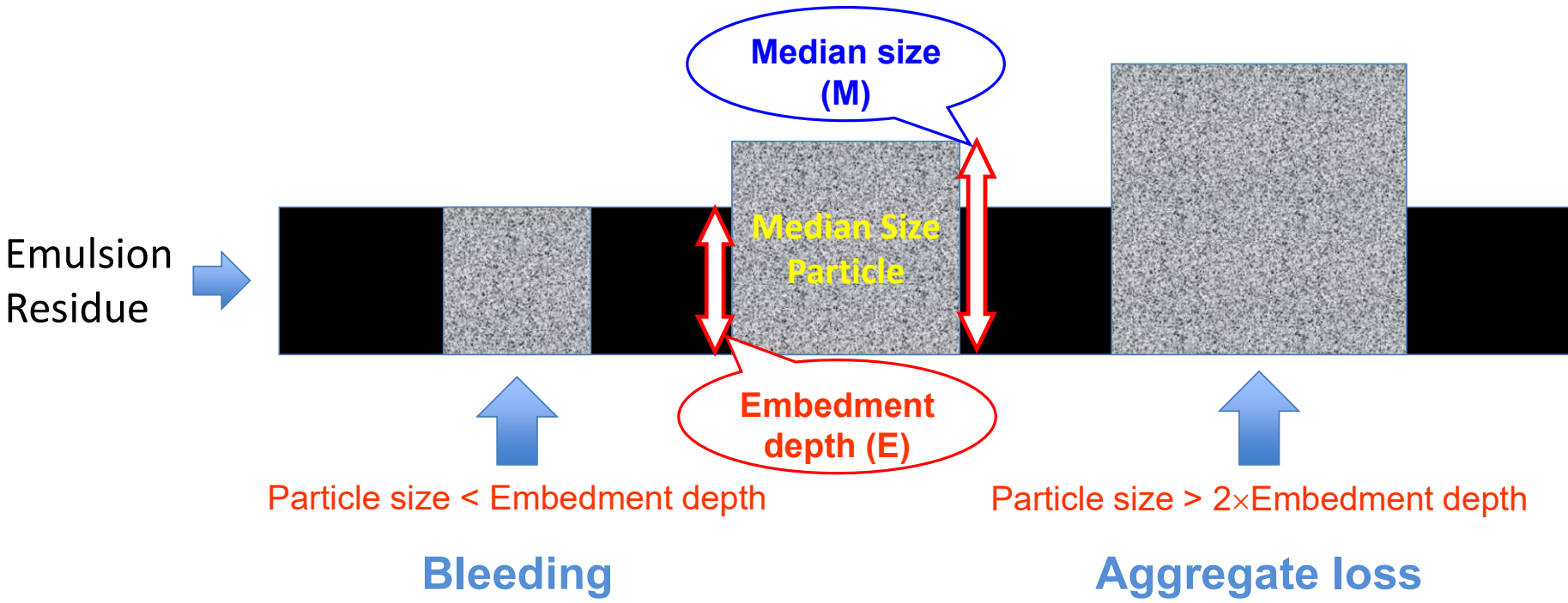


# Effect of Gradation on Aggregate Loss

*After 13k MMLS3 Cycles*

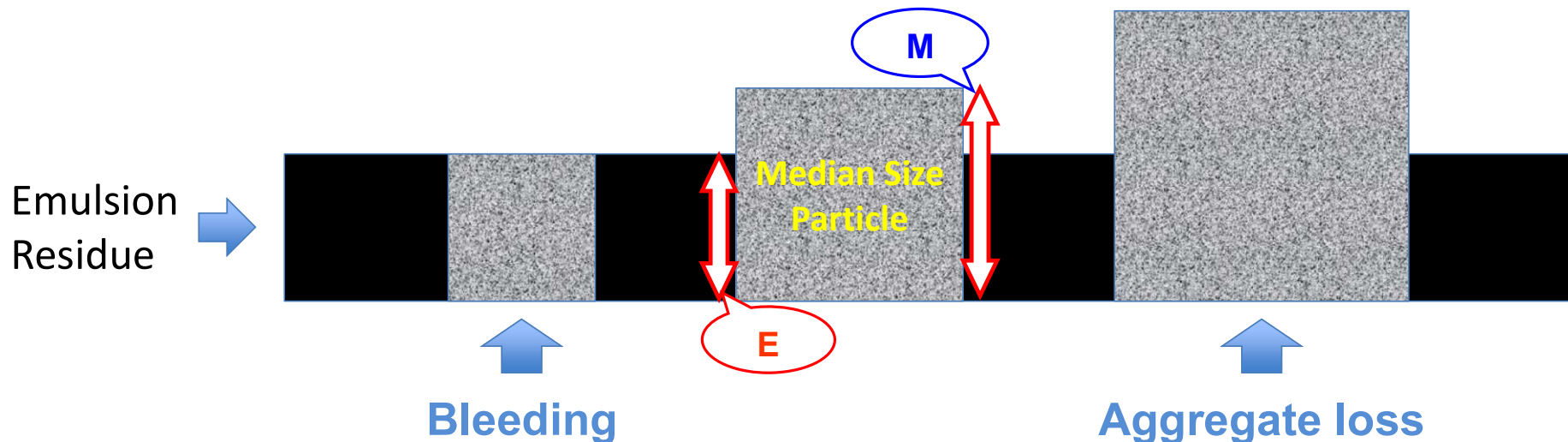


# Aggregate Embedment Depth

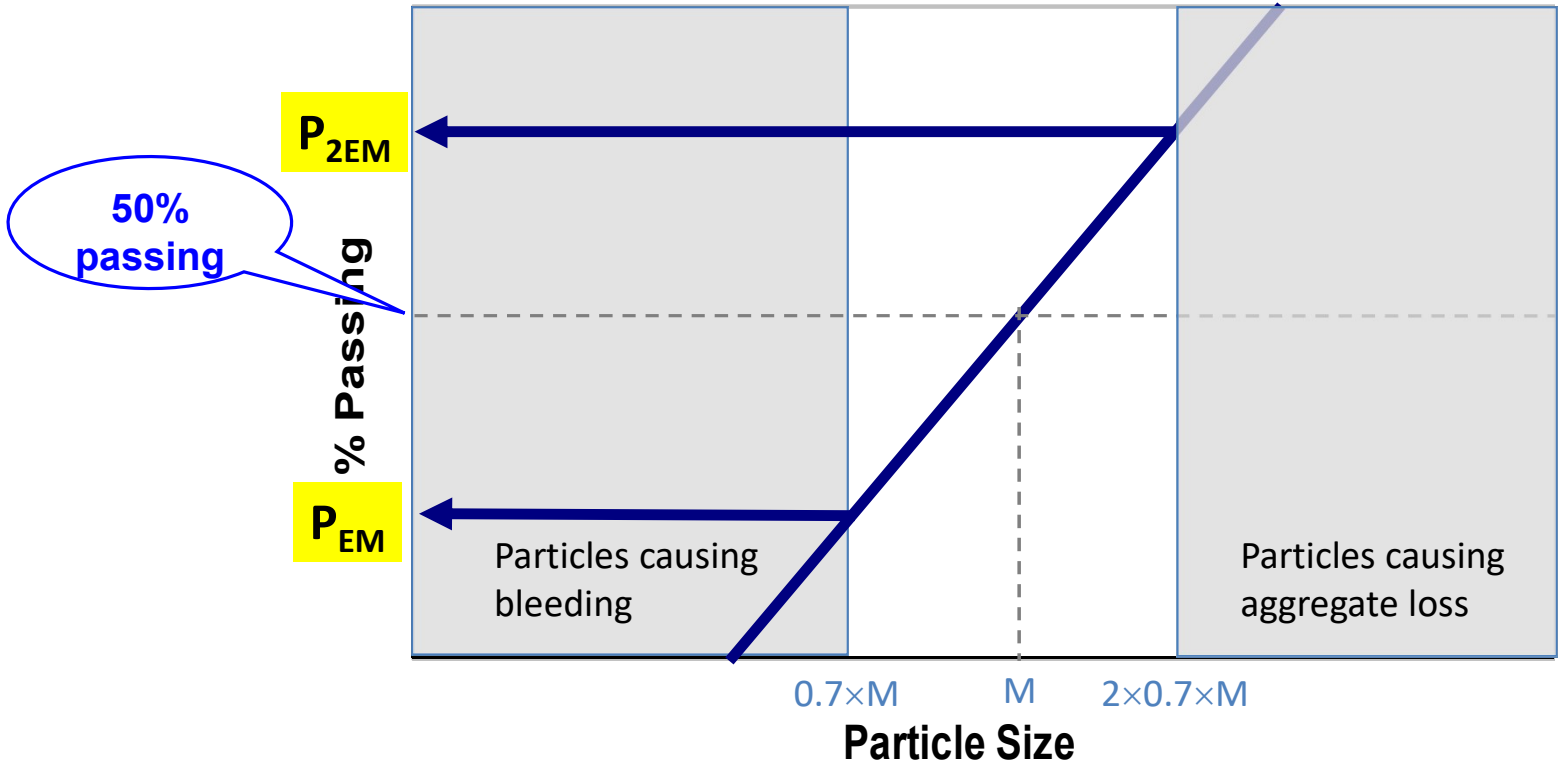


# McLeod's Chip Seal Failure Criteria

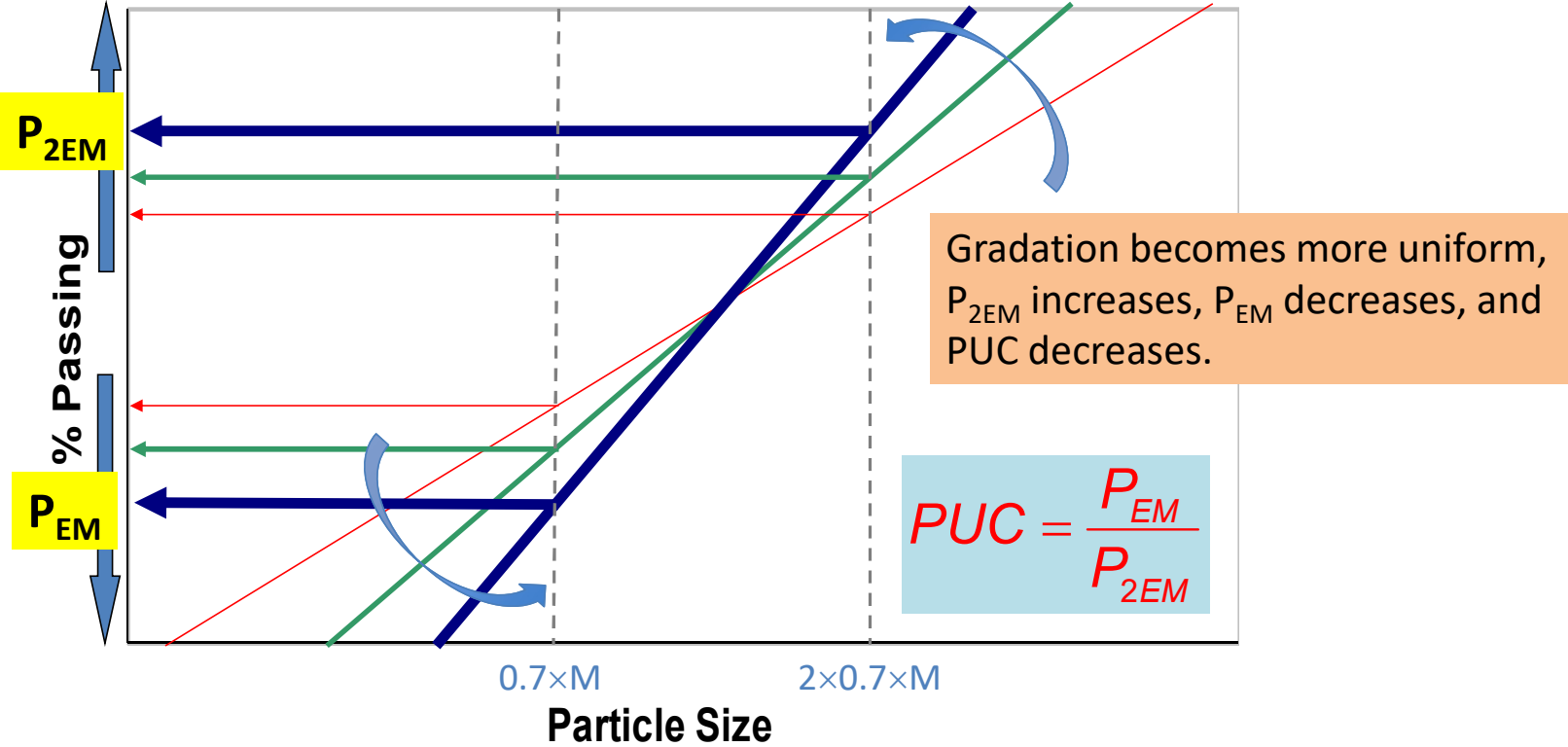
- ❑ Optimum embedment depth ( $E$ ) = Median particle size ( $M$ )  $\times$  (0.65-0.85) =  $0.7 \times M$
- ❑ Size of particles that will cause bleeding  $<$  Embedment depth =  $0.7 \times M$
- ❑ Size of particles that will cause aggregate loss  $>$  2  $\times$  Embedment depth =  $1.4 \times M$



# Performance Uniformity Coefficient



# Performance Uniformity Coefficient



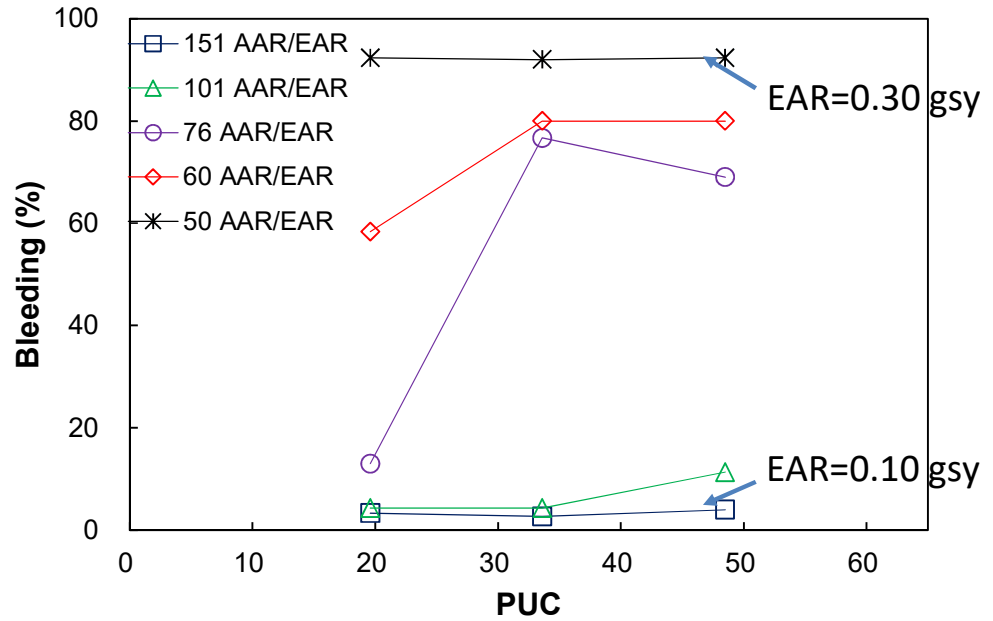
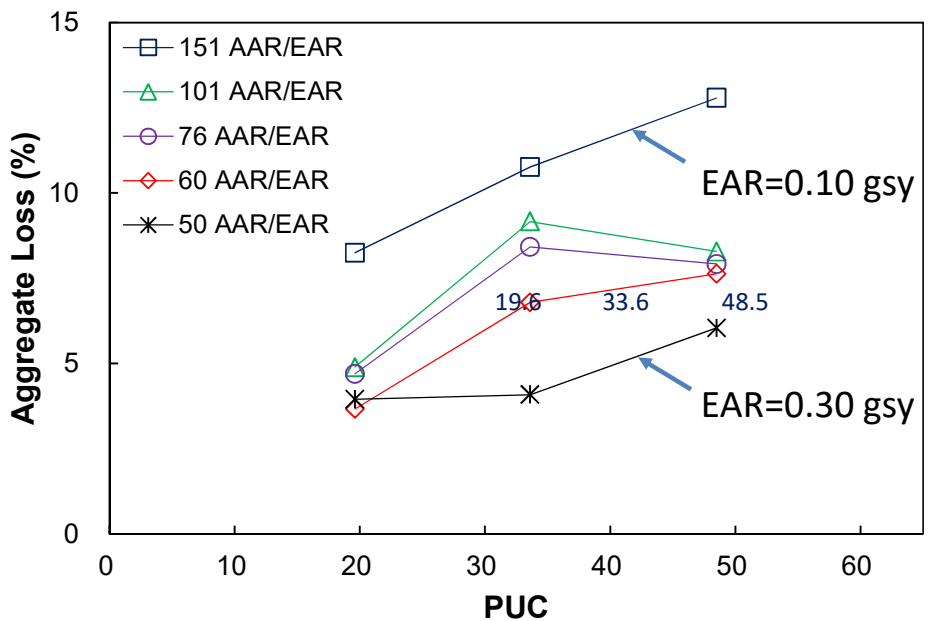
**A lower PUC yields less bleeding and less aggregate loss.**





# Effect of PUC on Chip Seal Performance

## Granite 78M Aggregate



- Aggregate Application Rate (AAR) = 15.1 lb/yd<sup>2</sup>
- Emulsion Application Rate (EAR) = 0.10, 0.15, 0.20, 0.25, and 0.30 gal/yd<sup>2</sup>



# Desirable Emulsion Properties



# Material Selection

## *Emulsion*

### ❑ Important considerations

- Set rate – Rapid Setting
- Charge selected based on aggregate type
  - Cationic emulsions generally outperform anionic emulsions because they are less sensitive to weather, inherently have antistripping qualities, and are electrostatically compatible with more types of aggregate.
- Most often high viscosity (2) – CRS-2
- Often contain modification – CRS-2L or CRS-2P



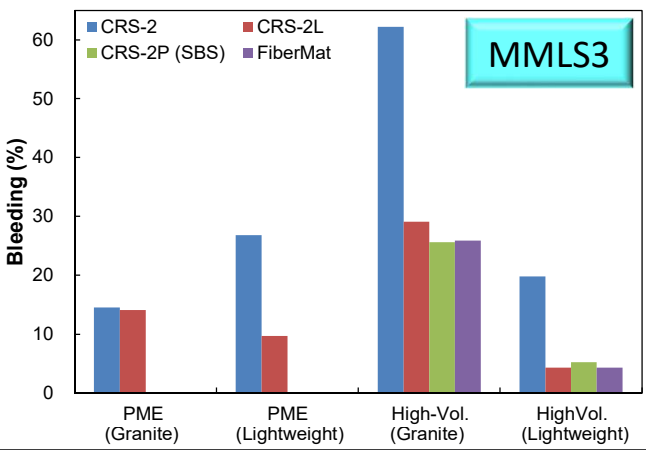
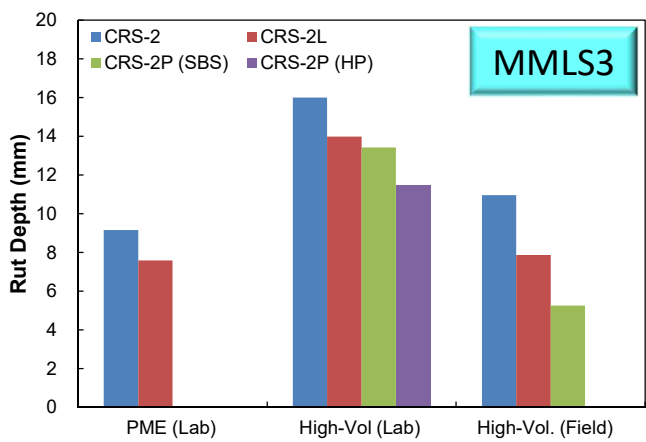
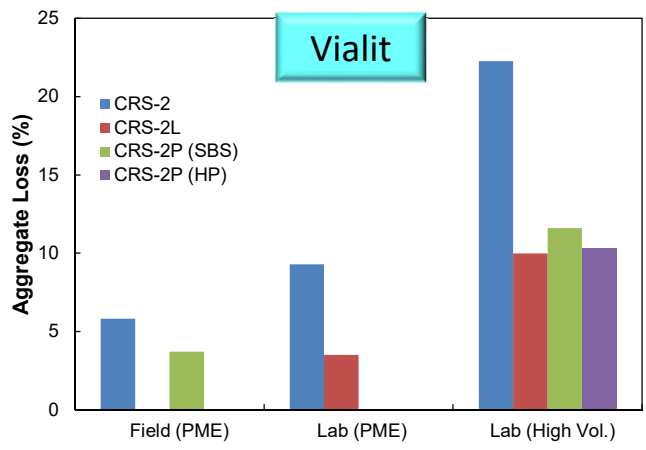
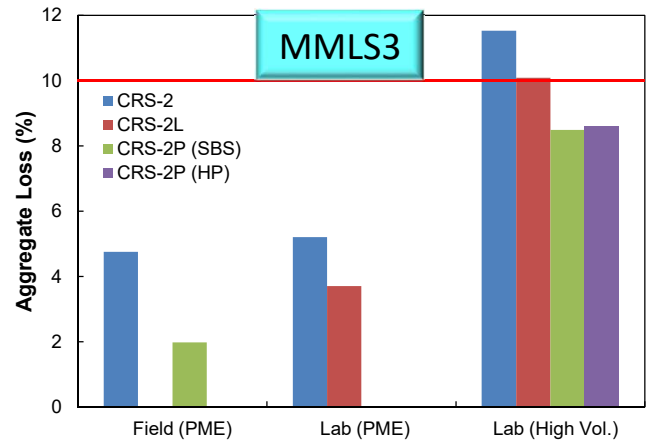
# Material Selection

## *Emulsion*

- ❑ High float emulsions (HF)
  - Pass “float test”
  - Prevents flowing at high temperatures
  - Allow for a thicker residual asphalt film on the aggregate
  - Can be used with “dirty” aggregate (up to 5% fines)

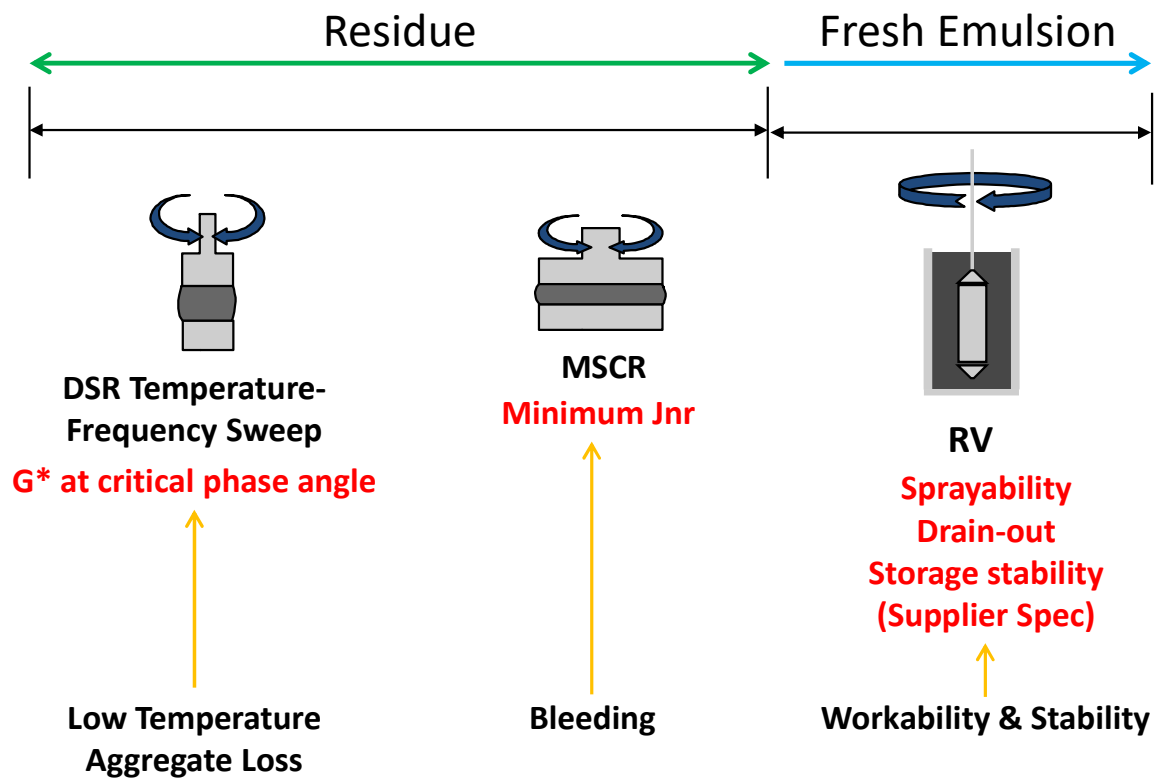


# Effect of Polymer Modification of Emulsion



# Emulsion PG Tests for **Chip Seal Emulsions**

*Developed under NCHRP 9-50 (Kim, Adams, Castorena, Illias)*



# EPG Limit Summary

Material	PG Test	Performance Parameter	Traffic Level	Test Temp. Range	EPG Limit
Fresh Emulsion	RV	Separation Ratio	N/A	60°C	0.5 to 1.5
		Stability Ratio			Maximum 2
		Sprayability			Maximum 400 cP
		Drainout			Minimum 50 cP
Emulsion Residue	DSR MSCR	Maximum $J_{nr}$ @ 3.2 kPa	Low	High	< 8 kPa <sup>-1</sup>
			Med		< 5.5 kPa <sup>-1</sup>
			High		< 3.5 kPa <sup>-1</sup>
	DSR Frequency Sweep	Maximum $ G^* $ @ $\delta c$	Low	5°C and 15°C	< 30 MPa
			Med		< 20 MPa
			High		< 10 MPa



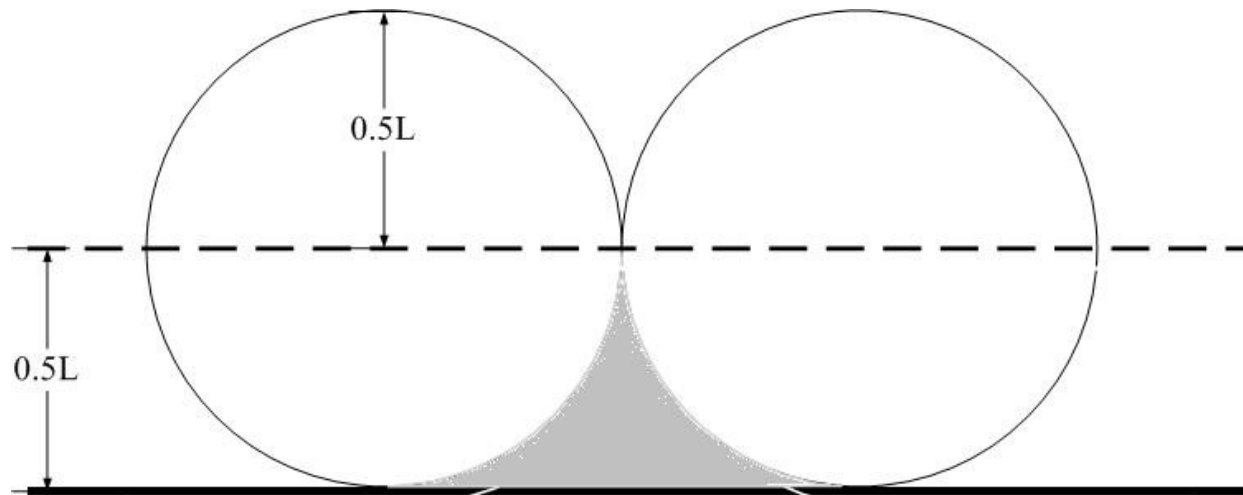
# Performance-Engineered Mix Design





## 50% Initial Embedment Concept

- Design to fill up subsurface voids (grey area)
- Subsurface voids account for ~50% embedment
- Traffic densification causes the embedment depth to increase to about 70%.

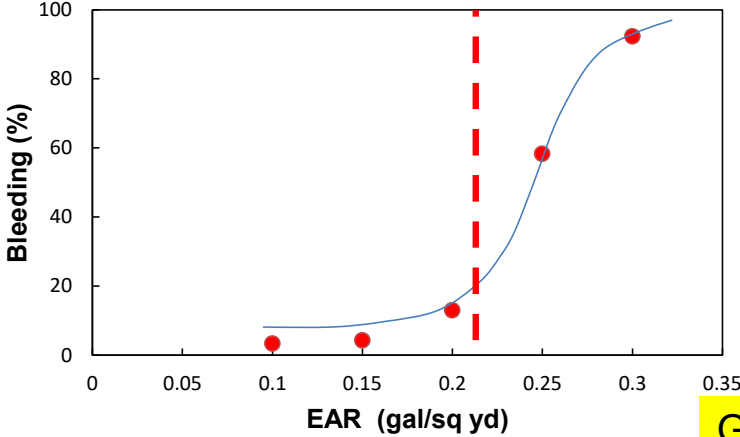


# Recommended Mix Design Procedure

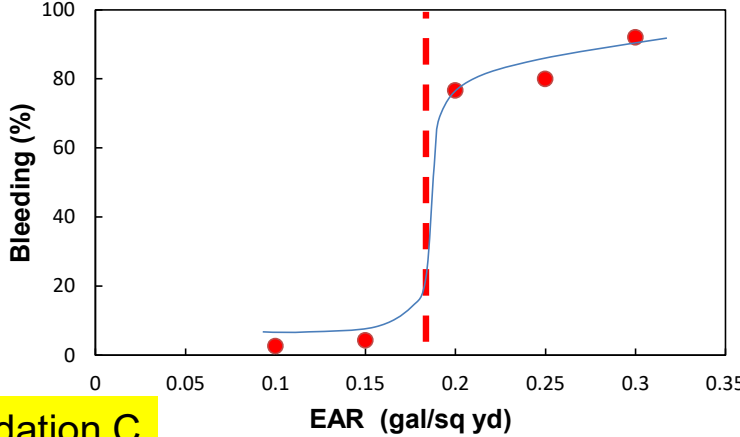
- ❑ Determine Design Aggregate Application Rate
  - Modified Board Test (305 mm by 508 mm board)
- ❑ Determine Design Emulsion Application Rate
  - Laser scan of Modified Board Test
  - Volumetric calculations
  - Adjust for existing surface absorption
  - Adjust for aggregate absorption
  - Consider penetration adjustment based on surface hardness
    - Penetration Ball Test (New Zealand 2005)
  - Consider steep grade adjustment (experience based)



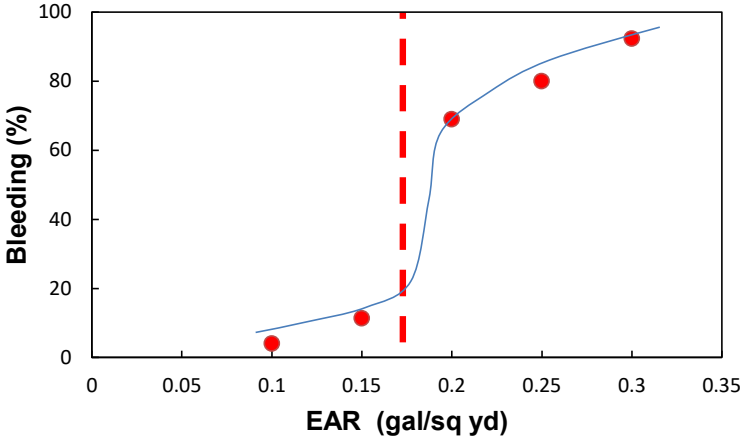
Gradation A



Gradation B



Gradation C



Granite  
78M

Optimum EAR  
from PEMD



# Optimal Rolling Protocols



# Roller Types Used



**Steel Wheel Roller**



**Pneumatic Tire Roller**

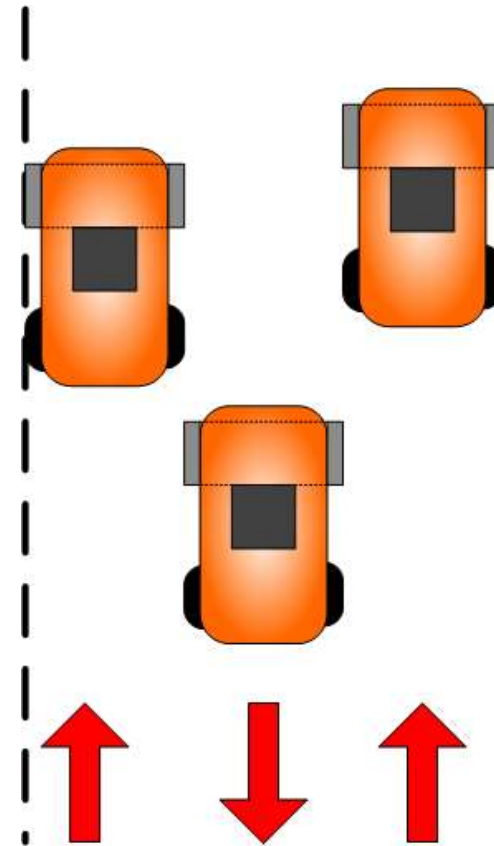


**Combination Roller**

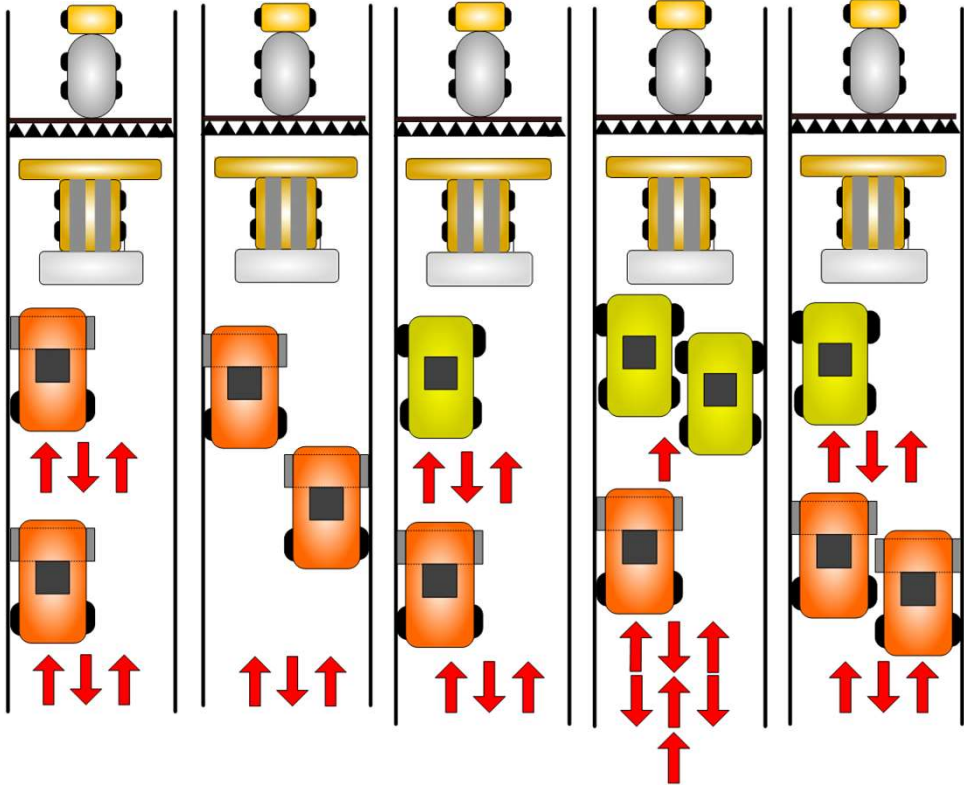


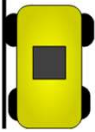
# Coverage vs. Pass

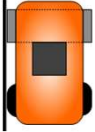
- ❑ Number of coverages = Number of roller passes on the *same* location
- ❑ 3 passes in zigzag pattern = 1 coverage



# Rolling Pattern Study



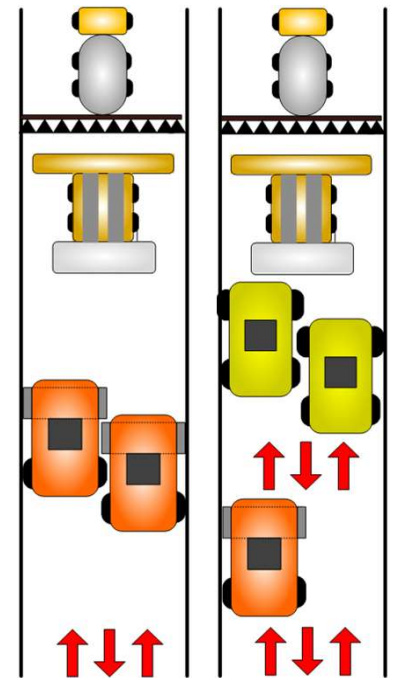
 |  
Pneumatic Tire Roller

 |  
Combination Roller



# Optimal Rolling Protocols

- ❑ Pneumatic tire roller and combination roller recommended
- ❑ Optimal number of rolling coverages of three
- ❑ No rolling required for the bottom layer of triple seal
- ❑ Recommended rolling protocols
  - Two roller case: Two combination rollers side-by-side
  - Three roller case: Two pneumatic tire rollers side-by-side followed by one combination roller



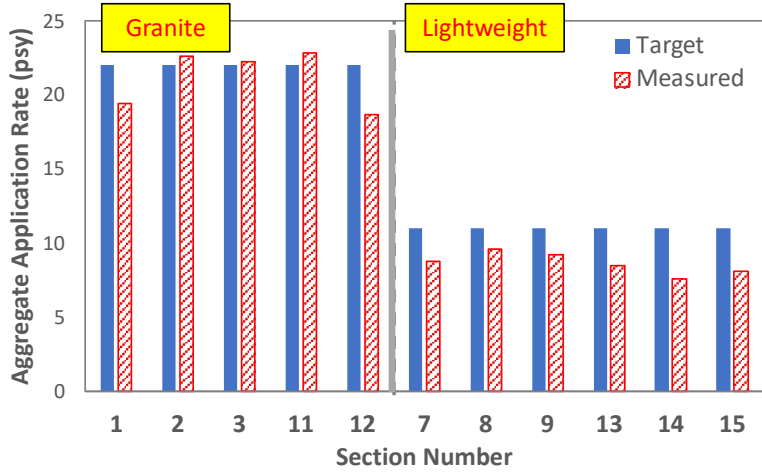
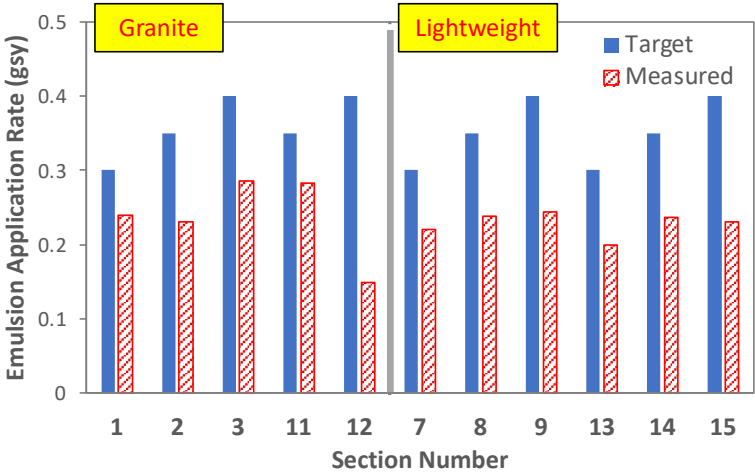


# Construction Variability of Chip Seals

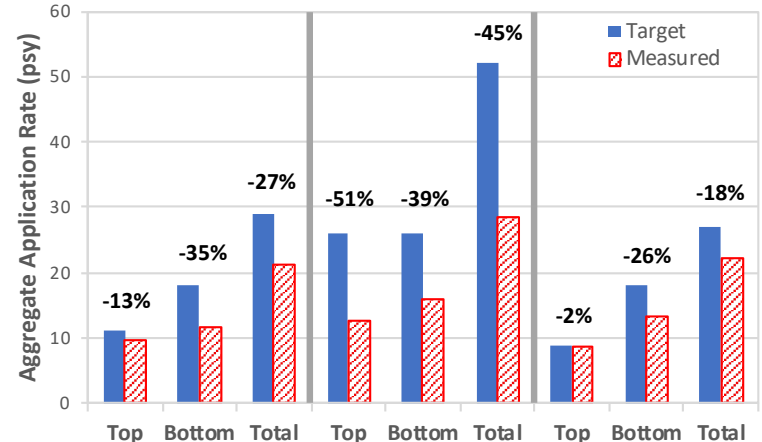
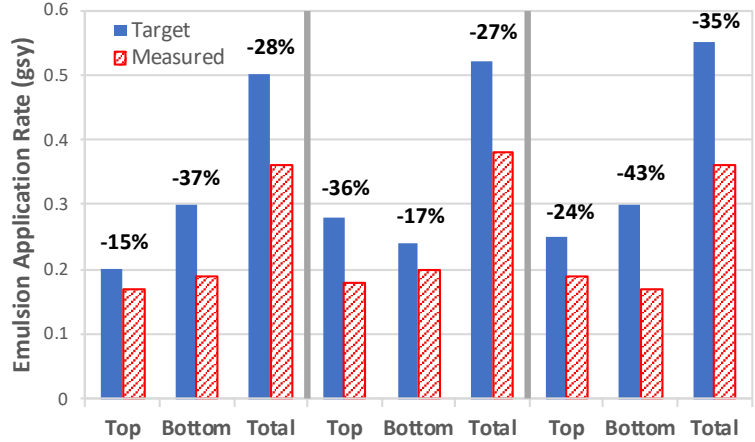


# Field Material Rate Variability

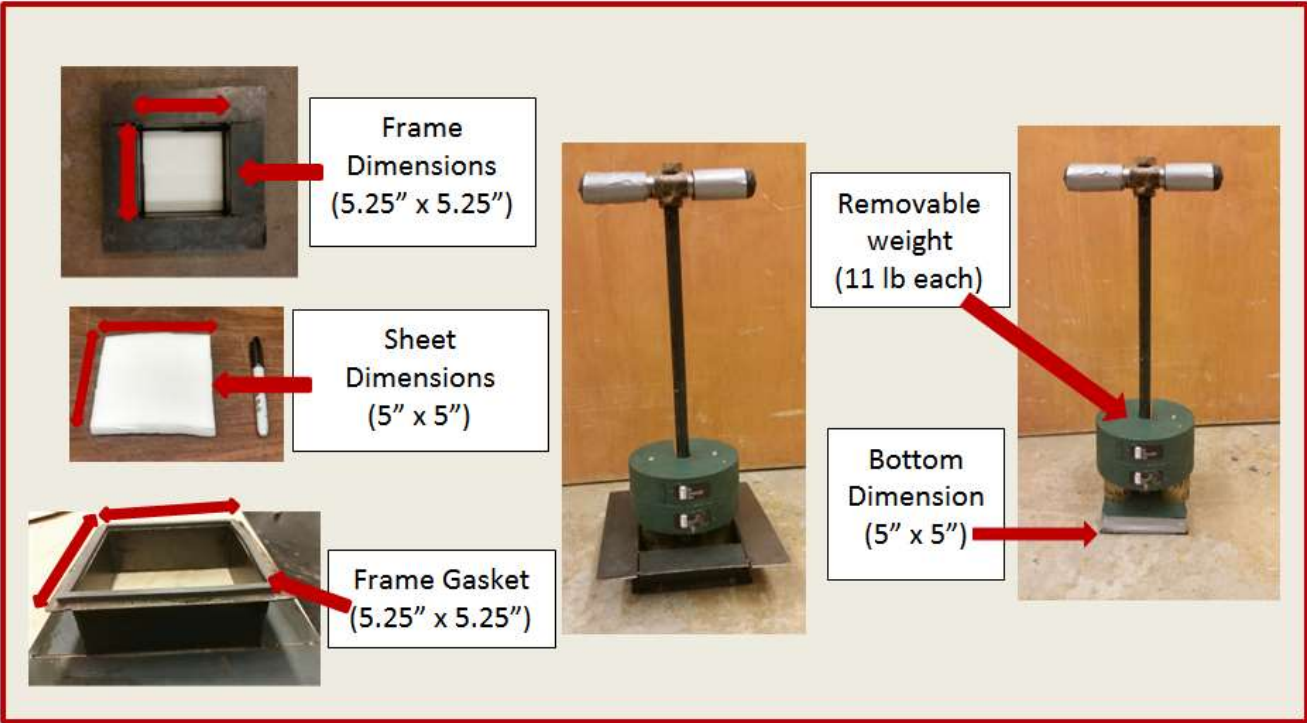
By NCDOT (2008)



By Contractors (2016)



# Tack Lifter



# Performance-Related QA Specifications



# PRS for Chip Seals (NCHRP 10-82A)

Acceptance Quality Characteristics	Related Performance Measure	Proposed Test Method	Test Parameter
Emulsion-Aggregate Adhesive Strength	Aggregate Loss	Vialit Test (Lab)	% Aggregate Loss
Gradation	Aggregate Loss	Gradation Analysis of Vialit Samples (Lab)	Performance Uniformity Coefficient
Emulsion Application Rate	Aggregate Loss and Bleeding	Tack Lifter or Ignition Oven on Vialit Samples	% Difference from Target EAR
Aggregate Application Rate	Aggregate Loss and Bleeding	Ignition Oven on Vialit Samples	% Difference from Target AAR



# Key Implementation Points

## ***Aggregate***

- ❑ Importance of uniform gradation (PUC as the specification)
- ❑ Fine content less than 1.5%

## ***Emulsion***

- ❑ Use of polymer modified emulsion strongly recommended
  - Excellent aggregate retention, bleeding, rutting, and low temperature performance of polymer-modified chip seals
  - Faster curing behavior with better long term adhesion strength



## Key Implementation Points – Cont'd

### Rolling

- ❑ Pneumatic tire roller and combination roller recommended
- ❑ Optimal number of rolling coverages of three
- ❑ No rolling required for the bottom layer of triple seal
- ❑ Recommended rolling protocols:
  - Two roller case: Two combination rollers side-by-side
  - Three roller case: Two pneumatic tire rollers side-by-side followed by one combination roller



## Key Implementation Points – Cont'd

### *Mix Design*

- ❑ Aggregate application rate (AAR) from the modified board test (305 mm by 508 mm board) – minimum three replicates
  - Traffic whip off factor
  - Wet aggregate
- ❑ Laser profiler to determine emulsion application rate (EAR) using the 50% initial embedment depth
  - Aggregate absorption
  - Absorption into existing pavement surface





## Key Implementation Points – Cont'd

### *Specifications*

- ❑ Emulsion PG specifications for chip seals, microsuffacings, and fog seals (NCHRP 09-50)
  - Rotational viscometer and DSR
- ❑ Performance-Related Specification for chip seals



## Key Implementation Points – Cont'd

### **Construction**

- Significant variability in AAR and EAR even with pre-construction calibration
- Chip seal construction best practices document
- Chip seal certification and QC/QA program





Thank you!

Questions?